

## Technical Data Sheet

### Hifax HSBMCB1158 PC/2 RXF BLK



Polypropylene Compounds

#### Product Description

Hifax HSBMCB1158PC/2 RXF BLK is a high melt flow, 1,200 MPa flexural modulus, mineral filled thermoplastic elastomeric olefin (TEO) resin that has a unique balance of flow and rigidity. It is typically used for molded in color exterior fascia applications.

|                          |                                                                                                                                    |
|--------------------------|------------------------------------------------------------------------------------------------------------------------------------|
| <b>Application</b>       | Bumpers; Exterior Automotive Applications                                                                                          |
| <b>Market</b>            | Automotive                                                                                                                         |
| <b>Processing Method</b> | Injection Molding                                                                                                                  |
| <b>Attribute</b>         | Good Dimensional Stability; Good Flow; Good Moldability; Good Stiffness; High Impact Resistance; Low Temperature Impact Resistance |

| Typical Properties                                        | Nominal Value | Units             | Test Method   |
|-----------------------------------------------------------|---------------|-------------------|---------------|
| <b>Physical</b>                                           |               |                   |               |
| Melt Flow Rate, (230 °C/2.16 kg)                          | 25            | g/10 min          | ISO 1133-1    |
| Density, (23 °C)                                          | 0.98          | g/cm <sup>3</sup> | ISO 1183-1    |
| <b>Mechanical</b>                                         |               |                   |               |
| Flexural Modulus                                          | 1200          | MPa               | ISO 178       |
| Tensile Stress at Yield                                   | 18            | MPa               | ISO 527-1, -2 |
| Tensile Strain at Yield                                   | 10            | %                 | ISO 527-1, -2 |
| <b>Thermal</b>                                            |               |                   |               |
| Deflection Temperature Under Load, (0.45 MPa, Unannealed) | 85            | °C                | ISO 75B-1, -2 |
| <b>Additional Information</b>                             |               |                   |               |
| Mold Shrinkage                                            |               |                   | ISO 294-4     |

Please contact LyondellBasell for shrinkage recommendations.

